

## HLT1800

### Two-part, Dispensable Thermal Gap Filler with High Thermal Conductivity

#### BENEFIT AND FEATURES

- Good dispensing and thixotropy properties for automated assembly processes
- Excellent surface wetting
- High compressibility for low stress applications
- Low density
- Proven long term reliability

#### OVERVIEW

Honeywell HLT1800 is two-part, dispensable thermal gap filler with low viscosity and good thixotropy properties. HLT1800 is formulated to balance thermal performance, phase separation and dispensing property. With its high compressibility, it is designed to minimize thermal resistance at interfaces and maintain excellent performance through reliability testing. The material is available in 200+200cc syringes, 1+1 gal and 5+5 gal jars.



#### TYPICAL APPLICATIONS

- EV battery package
- Automotive electronics
- Telecommunications
- LED lighting

#### STORAGE & USE

Shelf Life 6 months at 0-35°C, <65%RH

Property	HLT1800	Test Method
Specific Gravity	2.0	ASTM D792
Viscosity (cps@25°C)	300000	ASTM D2196 (Brookfield Viscometer, #7 spindle, 10rpm)
Hardness (Shore00)	50	ASTM D2240
Operation time(25°C)	2hours	-
Thermal Conductivity (W/m-K)	1.8	ASTM D5470
Thermal Impedance (°C-in <sup>2</sup> /W) (1mm@10psi) (Typical Value)	0.8	ASTM D5470
Dielectric Strength (KV/mm)	>10	ASTM D149
Volume Resistivity(Ω-cm)	>1.0×10 <sup>13</sup>	ASTM D257
Minimum BLT(mm)	0.2	Hon Internal
Cure Schedule	25°C (hr)	18
	120°C (min)	30
Color	Part A: Yellow Part B: White	Visual

#### Honeywell Electronic Materials

USA: 1-509-252-2102  
 China: 400-840-2233  
 Germany: 49-5137-999-9199  
 Japan: 81-3-6730-7092  
 Korea: 82-2-3483-5076  
 Singapore: 65-6580-3593  
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